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Burles

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Pei Reng Jeng, et al.

Serial No. : 09/781,283

Filed : 13 February 2001

: Art Unit #2823

: Examiner:

Title : PLANARIZATION METHOD OF INTER-LAYER DIELECTRICS AND INTER-METAL DIELECTRICS

: M. Estrada

AMENDMENT

Mail Stop Non-Fee Amendment
Honorable Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

RECEIVED

MAY 12 2003

TECHNOLOGY CENTER 2800

Sir:

Responsive to the Official Action dated 10 February 2003, please amend the above-referenced Patent Application as follows:

IN THE CLAIMS:

Please replace Claims 1 and 9 with the "CLEAN COPY" of the amended

Claims as follows:

CLEAN COPY OF AMENDED CLAIMS

D1

1. (Four Times Amended) A planarization method of inter-layer dielectrics, comprising the steps of:
 - providing a semiconductor substrate including a field oxide, a source, a drain, and a gate formed thereon;



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PATENT TRADEMARK OFFICE